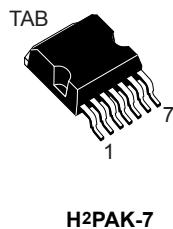


## Silicon carbide Power MOSFET 1200 V, 90 A, 21 mΩ (typ., $T_J = 25^\circ\text{C}$ ) in an H<sup>2</sup>PAK-7 package



### Features

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> typ.	I <sub>D</sub>
SCTH70N120G2V-7	1200 V	21 mΩ	90 A

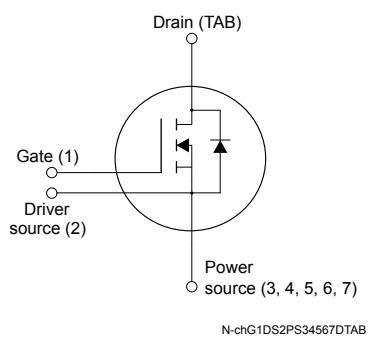
- Very high operating junction temperature capability ( $T_J = 175^\circ\text{C}$ )
- Very fast and robust intrinsic body diode
- Extremely low gate charge and input capacitances

### Applications

- Charger
- Power supply for renewable energy systems
- High frequency DC-DC converters

### Description

This silicon carbide Power MOSFET device has been developed using ST's advanced and innovative 2<sup>nd</sup> generation SiC MOSFET technology. The device features remarkably low on-resistance per unit area and very good switching performance. The variation of switching loss is almost independent of junction temperature.



#### Product status link

[SCTH70N120G2V-7](#)

#### Product summary

<b>Order code</b>	SCTH70N120G2V-7
<b>Marking</b>	SCT70N12
<b>Package</b>	H <sup>2</sup> PAK-7
<b>Packing</b>	Tape and reel

## 1 Electrical ratings

**Table 1.** Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	1200	V
$V_{GS}$	Gate-source voltage	-10 to 22	V
	Gate-source voltage (recommended operating values)	-5 to 18	
$I_D$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	90	A
	Drain current (continuous) at $T_C = 100^\circ\text{C}$	63	
$I_{DM}^{(1)}$	Drain current (pulsed)	253	A
$P_{TOT}$	Total power dissipation at $T_C = 25^\circ\text{C}$	469	W
$T_{stg}$	Storage temperature range	-55 to 175	$^\circ\text{C}$
$T_J$	Operating junction temperature range		$^\circ\text{C}$

1. Pulse width is limited by safe operating area.

**Table 2.** Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	0.32	$^\circ\text{C}/\text{W}$
$R_{thj-amb}$	Thermal resistance junction-ambient	50	$^\circ\text{C}/\text{W}$

## 2 Electrical characteristics

( $T_C = 25^\circ\text{C}$  unless otherwise specified).

**Table 3. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	1200			V
$I_{\text{DSS}}$	Zero gate voltage drain current	$V_{DS} = 1200 \text{ V}, V_{GS} = 0 \text{ V}$			10	$\mu\text{A}$
		$V_{DS} = 1200 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 150^\circ\text{C}$		100		
$I_{\text{GSS}}$	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = -10 \text{ to } +22 \text{ V}$		$\pm 10$		nA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 1 \text{ mA}$	1.90	2.45	4.90	V
$R_{\text{DS(on)}}$	Static drain-source on-resistance	$V_{GS} = 18 \text{ V}, I_D = 50 \text{ A}$		21	30	$\text{m}\Omega$
		$V_{GS} = 18 \text{ V}, I_D = 50 \text{ A}, T_J = 175^\circ\text{C}$		40		

**Table 4. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 800 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$	-	3540	-	pF
$C_{oss}$	Output capacitance		-	176	-	pF
$C_{rss}$	Reverse transfer capacitance		-	28	-	pF
$R_g$	Gate input resistance	$f = 1 \text{ MHz}, I_D = 0 \text{ A}$	-	1	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 800 \text{ V}, I_D = 50 \text{ A}, V_{GS} = -5 \text{ to } 18 \text{ V}$	-	150	-	nC
$Q_{gs}$	Gate-source charge		-	28	-	nC
$Q_{gd}$	Gate-drain charge		-	63	-	nC

**Table 5. Switching energy (inductive load - values based on HiP247 package)**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$E_{\text{on}}$	Turn-on switching energy	$V_{DD} = 800 \text{ V}, V_{GS} = -5 \text{ to } 18 \text{ V}, I_D = 50 \text{ A}, R_G = 3.4 \Omega$	-	1019	-	$\mu\text{J}$
$E_{\text{off}}$	Turn-off switching energy		-	378	-	

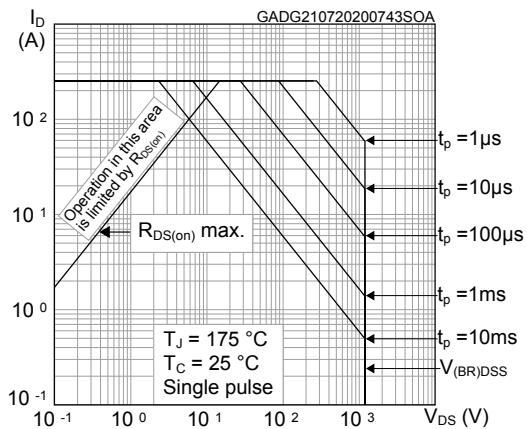
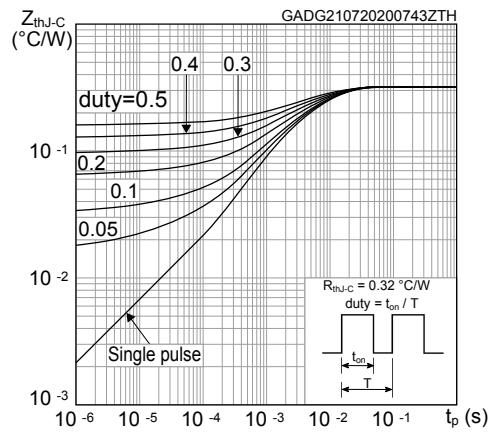
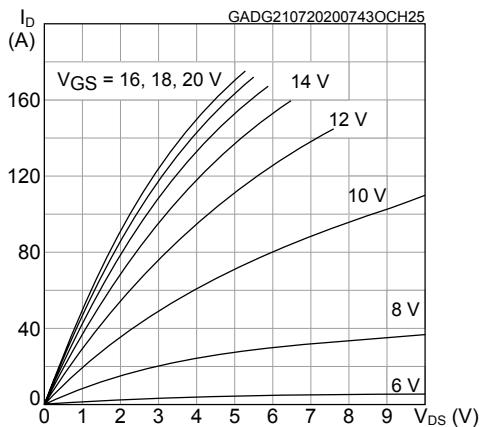
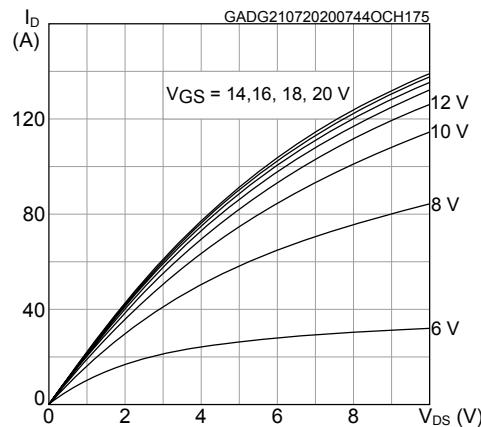
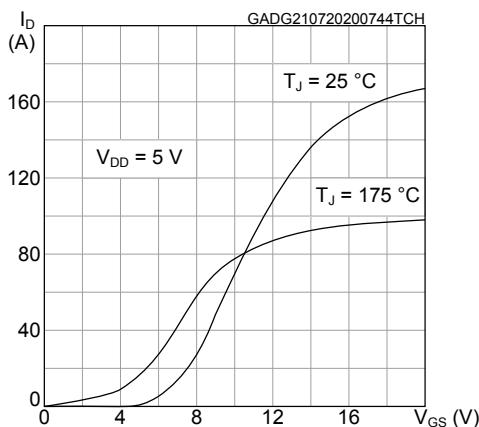
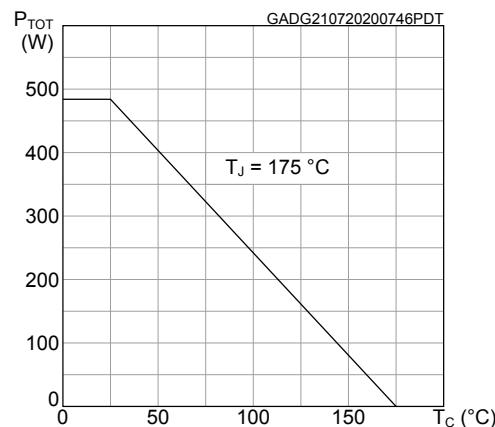
**Table 6. Switching times (values based on HiP247 package)**

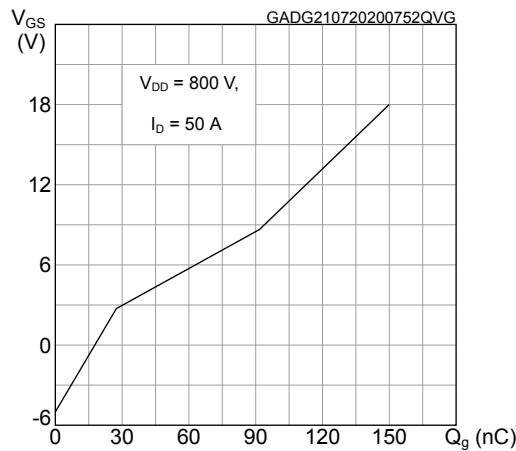
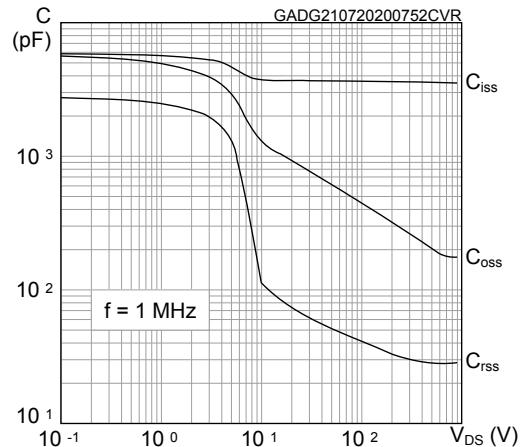
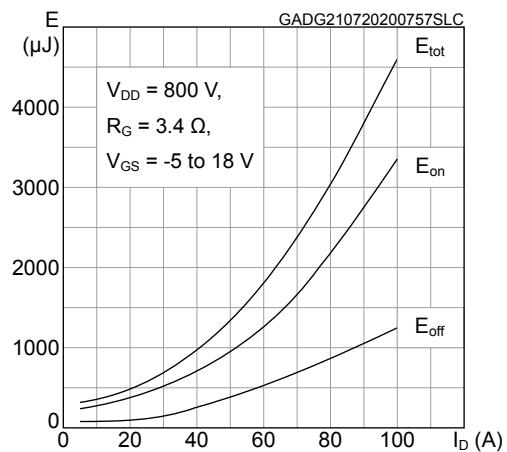
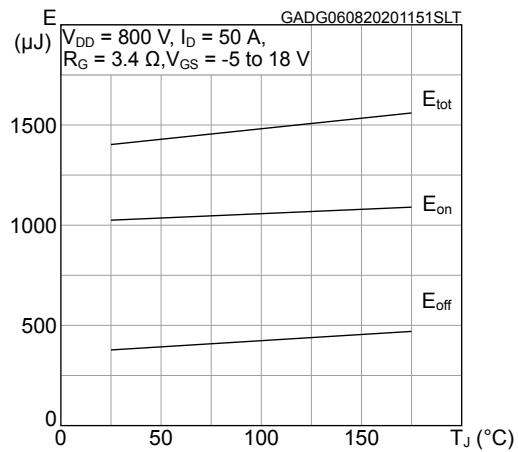
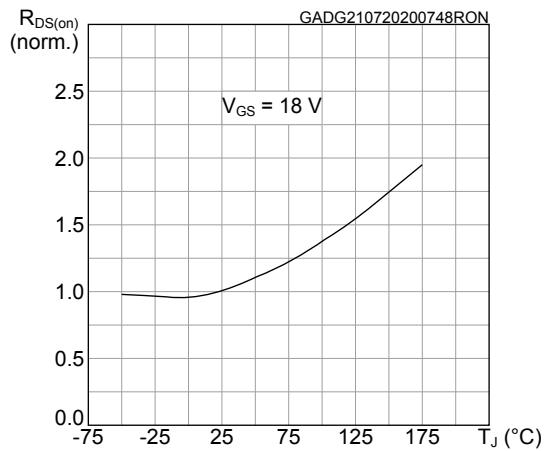
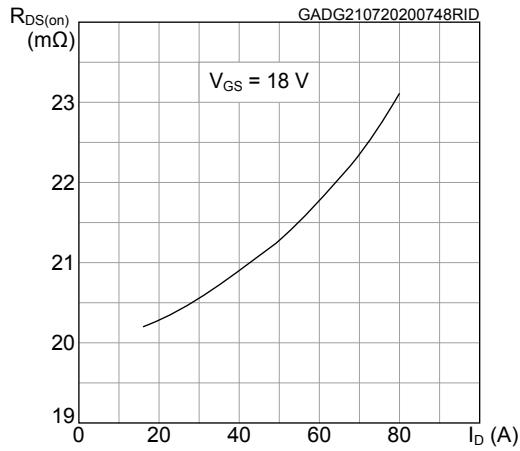
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(\text{on})}$	Turn-on delay time	$V_{DD} = 800 \text{ V}, I_D = 50 \text{ A}, R_G = 3.4 \Omega, V_{GS} = -5 \text{ to } 18 \text{ V}$	-	16	-	ns
$t_r$	Rise time		-	9.5	-	ns
$t_{d(\text{off})}$	Turn-off delay time		-	37	-	ns
$t_f$	Fall time		-	22	-	ns

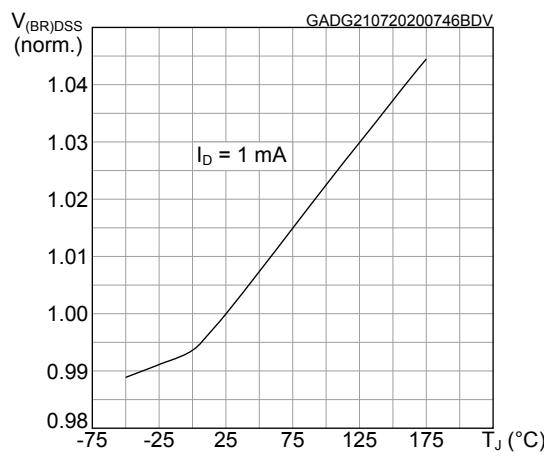
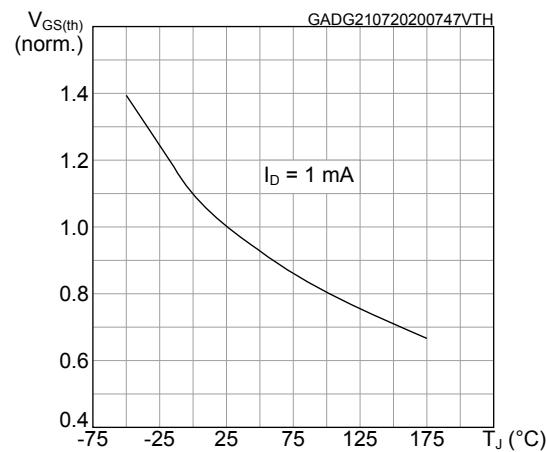
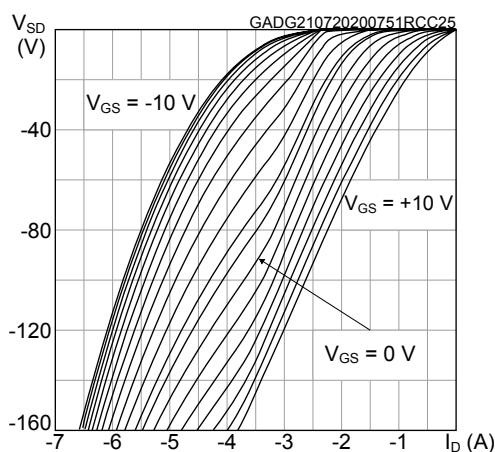
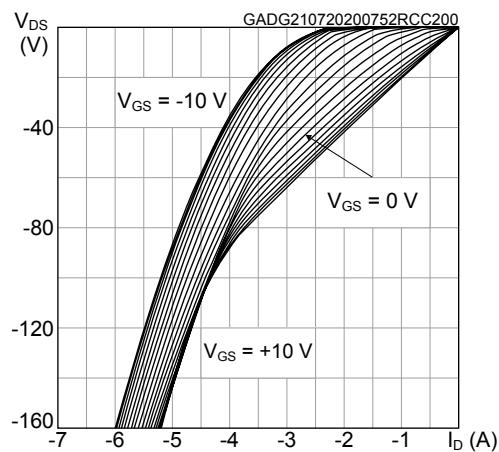
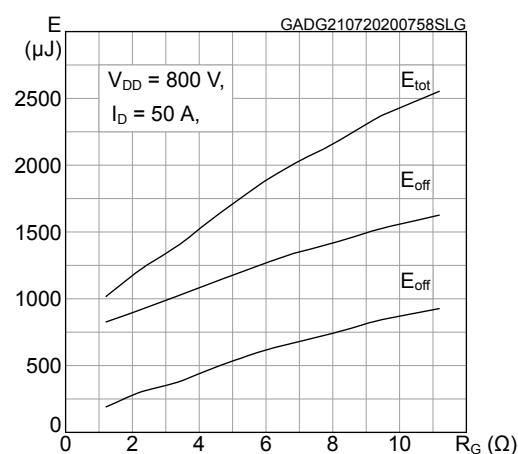
**Table 7. Reverse SiC diode characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V <sub>SD</sub>	Forward on voltage	I <sub>SD</sub> = 50 A, V <sub>GS</sub> = 0 V	-	2.7	-	V
t <sub>rr</sub>	Reverse recovery time		-	11.16	-	ns
Q <sub>rr</sub>	Reverse recovery charge		-	276	-	nC
I <sub>RRM</sub>	Reverse recovery current		-	40	-	A

## 2.1 Electrical characteristics (curves)

**Figure 1. Safe operating area**

**Figure 2. Maximum transient thermal impedance**

**Figure 3. Typical output characteristics ( $T_J = 25^\circ C$ )**

**Figure 4. Typical output characteristics ( $T_J = 175^\circ C$ )**

**Figure 5. Typical transfer characteristics**

**Figure 6. Total power dissipation**


**Figure 7. Typical gate charge**

**Figure 8. Typical capacitance characteristics**

**Figure 9. Typical switching energy vs drain current**

**Figure 10. Typical switching energy vs temperature**

**Figure 11. Normalized on-resistance vs temperature**

**Figure 12. Typical drain-source on-resistance**


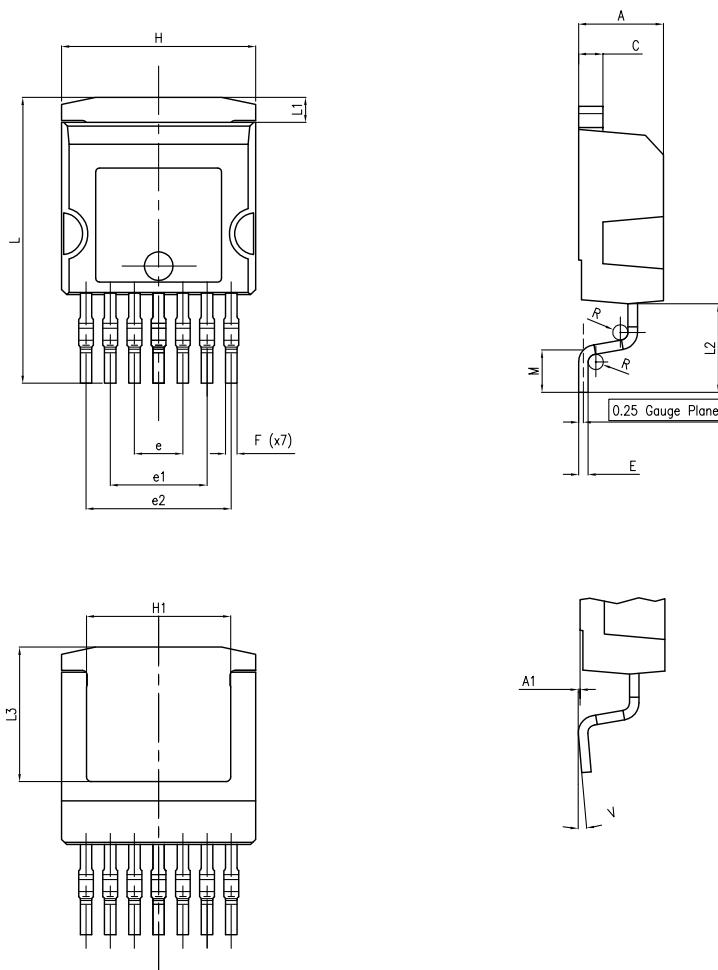
**Figure 13. Normalized breakdown voltage vs temperature**

**Figure 14. Normalized gate threshold voltage vs temperature**

**Figure 15. Typical reverse conduction characteristics (T<sub>J</sub> = 25 °C)**

**Figure 16. Typical reverse conduction characteristics (T<sub>J</sub> = 200 °C, based on HiP247 package)**

**Figure 17. Typical switching energy vs gate resistance**


## 3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 3.1 H<sup>2</sup>PAK-7 package information

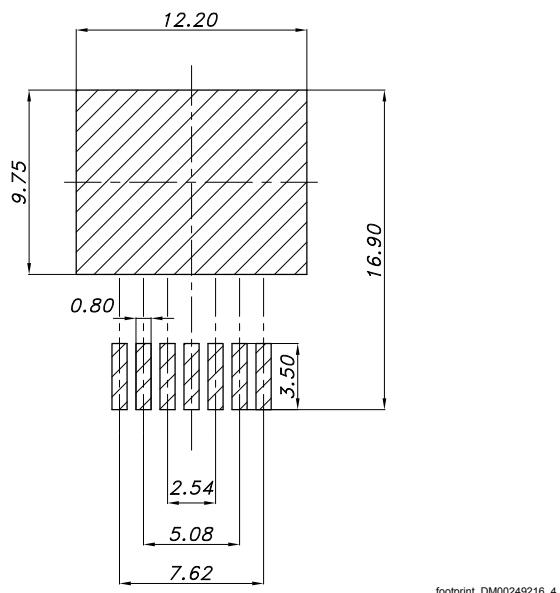
Figure 18. H<sup>2</sup>PAK-7 package outline



DM00249216\_4

**Table 8.** H<sup>2</sup>PAK-7 package mechanical data

Dim.	mm	
	Min.	Max.
A	4.30	4.80
A1	0.03	0.20
C	1.17	1.37
e	2.34	2.74
e1	4.88	5.28
e2	7.42	7.82
E	0.45	0.60
F	0.50	0.70
H	10.00	10.40
H1	7.40	7.60
L	14.75	15.25
L1	1.27	1.40
L2	4.35	4.95
L3	6.85	7.25
M	1.90	2.50
R	0.20	0.60
V	0°	8°

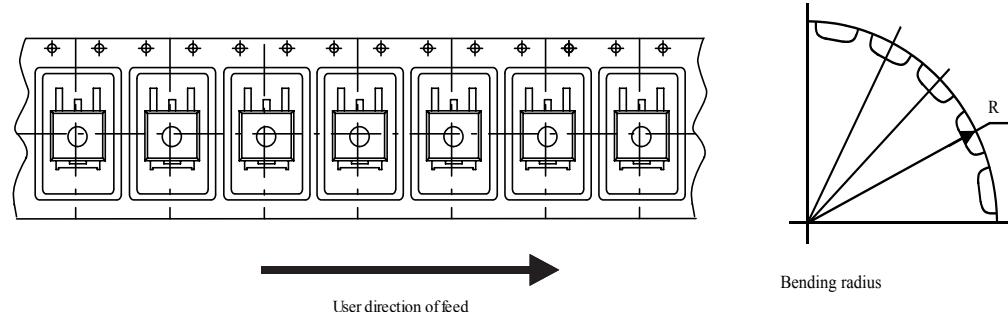
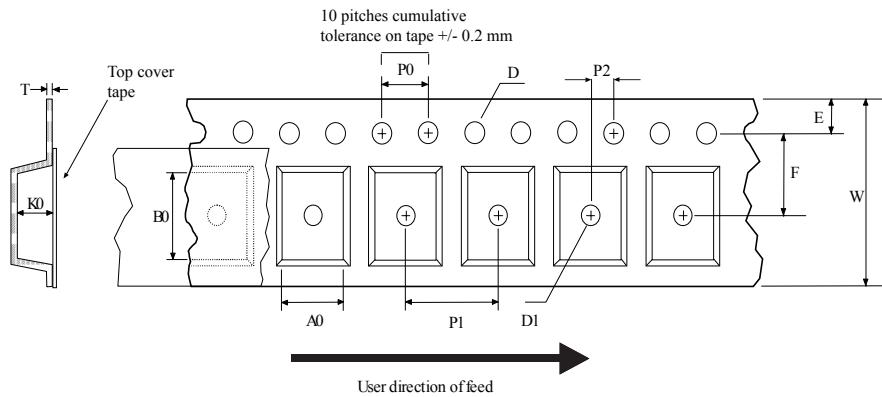
**Figure 19.** H<sup>2</sup>PAK-7 recommended footprint

footprint\_DM00249216\_4

Note: Dimensions are in mm.

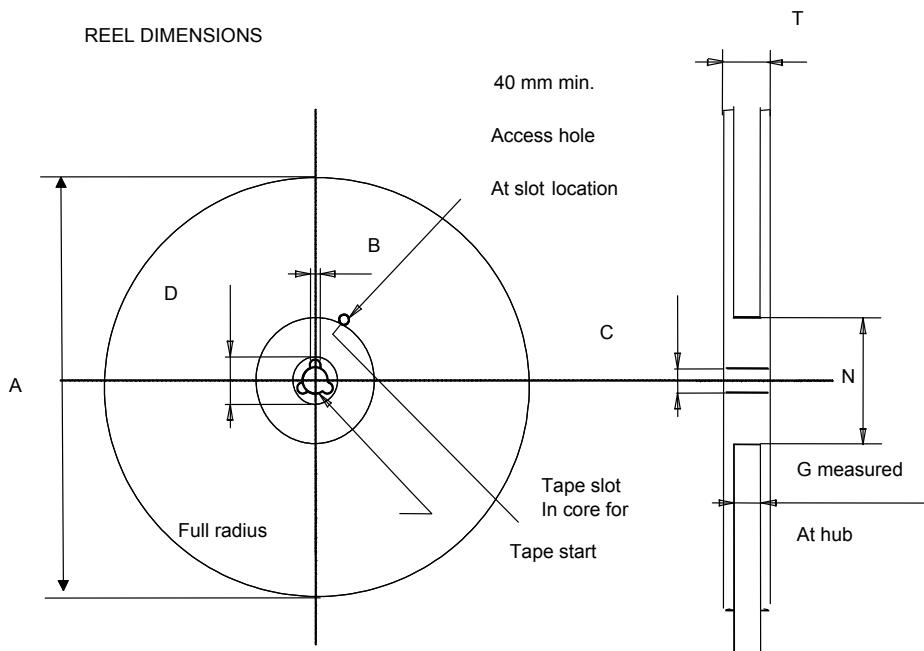
### 3.2 Packing information

Figure 20. Tape outline



Bending radius

AM08852v2

**Figure 21. Reel outline**

**Table 9. Tape and reel mechanical data**

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1		Base quantity	1000
P2	1.9	2.1		Bulk quantity	1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

## Revision history

**Table 10. Document revision history**

Date	Revision	Changes
11-Aug-2020	1	First release.

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